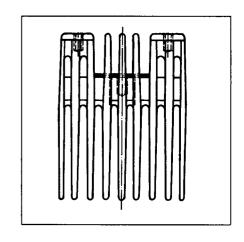




Туре	R <sub>thca</sub> @ natural cooling °C/W	P	R <sub>thca</sub> @ forced air cooling °C/W	V <sub>air</sub> /t m <sup>3</sup> /h	w g
K 0,55 - M 12 K 0,55 - M 16 K 0,55 - M 24	0,62 0,57 0,55	100	0,25 0,20 0,17	230	2000
K 1,1 - M 8 K 1,1 - M 12 K 1,1 - M 16	1,3 1,2 1,1	50	0,53 0,41 0,36	140	700
K3-M5 K3-M6 K3-M8 K3-M12	4,0 3,5 3,25 3,1	15			200
K5-M5 K5-M6 K5-M8	6,0 5,5 5,25	10			100
K9-M5 K9-M6	10,0 9,5	5			50

## Heatsinks

K 0,55 K 5 K 1,1 K 9 K 3

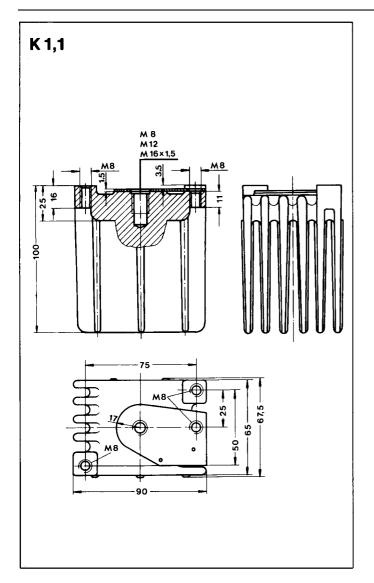


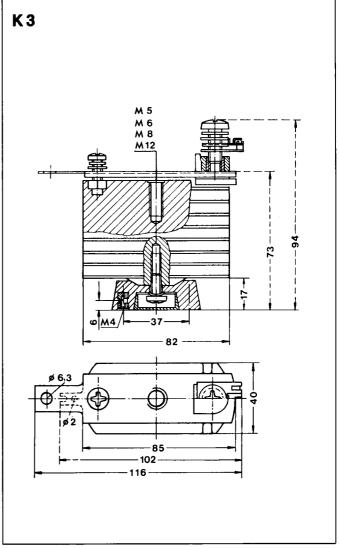
## K 0,55

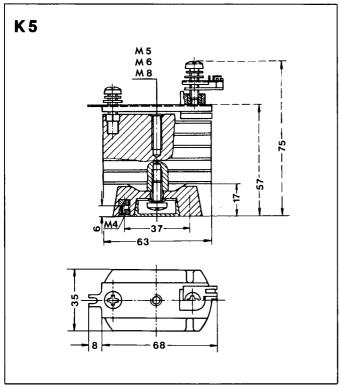
## **Features**

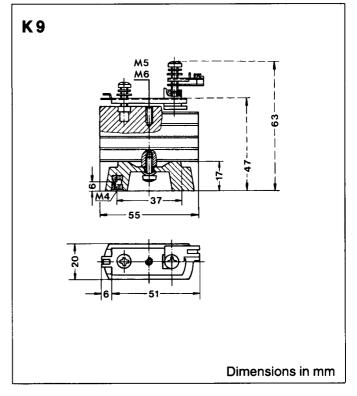
- Intended for stud mounted devices
- Mounting points are provided for additional accessories
- DIN standard series

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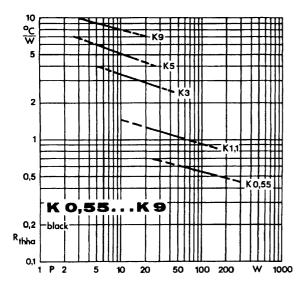
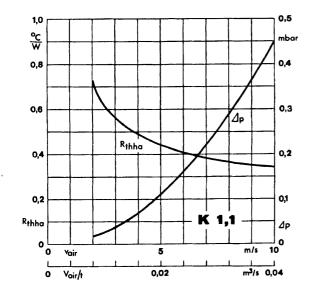


Fig. 1 Thermal resistance vs. dissipated power



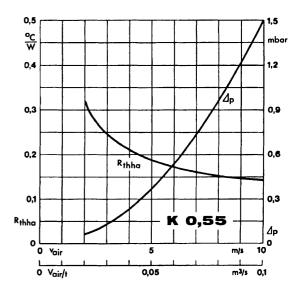


Fig. 4 a Thermal resistance and pressure drop vs. air flow Fig 4 b Thermal resistance and pressure drop vs. air flow